MBE
KOMPDNENTEN｜DR．EBERL

## ロCTロPடபS 4ロロ／MRE SYSTEM

■ Compact，versatile MBE system for R\＆D
■ Applications：III－V，II－VI or other materials
－ 10 source ports，various source options including e－beam evaporators

■ 1＂，2＂，3＂or $1 / 4$ wafer substrate size
－$<5 \times 10^{-11}$ mbar base pressure
－LN2 cooling shroud
■ In－situ monitoring


OCTOPLUS 400 MBE System


OCTOPLUS 400 control system

The OCTOPLUS 400 series is a very compact and versatile MBE system with low running costs．It can be integrated into small size R\＆D laboratories due to its small footprint．It provides convenient source access and excellent serviceability due to its open design．High quality epitaxial layers on substrates up to 3 inch in diameter can be deposited．

The OCTOPLUS 400 system is ideally suited for cutting edge research on a wide variety of materials including GaAs，phosphides，antimonides，nitrides，graphene and topological insulators．

It can be easily adapted to small wafer segments as well as to 1,2 or 3 inch wafers．The field－proven vertical chamber design of the OCTOPLUS 400 plus various state－of－the－art components allow layer by layer precise MBE growth．

The MBE process control software integrates easy recipe writing，automated growth control and extensive data recording．

All our MBE products are designed and manufactured by Dr．Eberl MBE－Komponenten GmbH．The products are cleaned and assembled in our own clean room environment．Each component is tested and outgassed under UHV conditions．Helium leak testing and operation at maximum conditions is performed to reach the high standard of our products．

Dr．Eberl MBE－Komponenten GmbH specializes in customized products．Due to more than 30 years experience in MBE technology we are able to offer individually designed system solutions which follow our customers＇needs．

The MBE systems are installed and acceptance tested by experienced MBE PhD experts．Extensive customer training is offered as an additional option．

KOMPDNENTEN | DR. EBERL

Technical Data

| Size of deposition chamber | $450 \mathrm{~mm} \mathrm{I.D}$. |
| :---: | :---: |
| Base pressure | < $5 \times 10^{-11}$ mbar |
| Pumping | cryopump, turbopump, TSP or ion getter pump |
| Cooling shroud | LN2 or other cooling liquid on request |
| Substrate heater temperature | up to $800^{\circ} \mathrm{C}, 1000^{\circ} \mathrm{C}$ or $1400^{\circ} \mathrm{C}$ |
| Substrate size | up to $3^{\prime \prime}$ diameter |
| Bakeout temperature | up to $200^{\circ} \mathrm{C}$ |
| Source ports | 10 source ports DN63CF (O.D. 4.5") |
| Source types | effusion cells, e-beam evaporators, sublimation |
|  | sources, valved cracker sources, gas sources |
| Shutters | soft-acting linear or rotary shutters |
| In-situ monitoring | ion gauge, QCM, pyrometer, RHEED, QMA |
| Sample transfer | linear transfer rod, manual or semi-automatic |
| Load lock | turbo-pumped, magazine with 6 substrates |
| MBE control software | Tusker |
| Service | system installation and acceptance testing |
| MBE training | by PhD MBE experts |

Examples for applications and corresponding sources

| Application | Effusion | Sublimation | Valved | Plasma | E-Beam |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  | Cells | Sources | Sources | Sources | Evaporators |
| Source type | WEZ, NTEZ | SUKO, SUSI | VACS, VGCS |  | EBVV |
|  | OME, HTEZ | HTS, DECO | VCS, VSCS |  |  |
| IIIN (As, Sb, P) | Ga, In, Al, Be | C, Si doping | As, P, Sb |  |  |
| IINI | $\mathrm{Zn}, \mathrm{Cd}, \mathrm{Be}$ |  | $\mathrm{S}, \mathrm{Se}, \mathrm{Te}$ | N-doping |  |
| IV | $\mathrm{Ge}, \mathrm{Sn}, \mathrm{Pb}$ | B, P, Sb doping |  |  | $\mathrm{Si}, \mathrm{Ge}$ |
| GaN | Ga, In, Al |  |  | N |  |
| Metals | $\mathrm{Cu}, \mathrm{Al}, \mathrm{Ni}, \mathrm{Co}, \ldots$ |  |  |  | Pt,Ta,Pd,Mo,W |
| Topological Insulators | $\mathrm{Ge}, \mathrm{Sb}, \mathrm{Te}$, |  | $\mathrm{Se}, \mathrm{Te}$ |  | B |
|  | Bi, GeSb |  |  |  |  |
| Graphene / Silicene |  | C, Si |  |  |  |
| Oxides | $\mathrm{Fe}, \mathrm{Ni}, \mathrm{Mn}, \mathrm{Bi}$, |  |  | 0 |  |
|  | Eu, Ga,... |  |  |  |  |
| Thin Film Solar Cell | $\mathrm{Cu}, \mathrm{Ga}, \mathrm{In}, \mathrm{Zn}$, |  | S, Se |  |  |
|  | $\mathrm{NaF}, \mathrm{Fe}, \mathrm{Sn}$ |  |  |  |  |

MBE components typically used in DCTDPLUS 400:


Substrate Manipulator


Effusion Cell


E-Beam Evaporator


Valved Cracker Source

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